

Claims:

- 1 1. A slider, comprising:
 - 2 a magnetic head coupled to the slider, the magnetic head having a first set of electrical
 - 3 pads to read data from a magnetic storage medium and a second set of electrical pads to write
 - 4 data to the magnetic storage medium;
 - 5 a charging electrical pad coupled to the slider separate from the magnetic head; and
 - 6 a charging electrical conductor coupled to the electrical pad to apply an electrical charge
 - 7 to the slider.
- 1 2. The slider of claim 1, wherein the charging electrical pad is coupled to a trailing edge of
- 2 the slider.
- 1 3. The slider of claim 1, wherein the charging electrical pad is coupled to the slider during a
- 2 wafer fabrication process.
- 1 4. The slider of claim 1, wherein the slider is coupled to a suspension.
- 1 5. The slider of claim 4, wherein the slider is electrically isolated from the suspension.
- 1 6. The slider of claim 5, wherein the slider is coupled to the suspension using an adhesive
- 2 with a high electrical resistance.

1 7. The slider of claim 1, wherein the slider is connected to an electronic feedback system,
2 the electronic feedback system to monitor an environmental condition of the slider.

1 8. The slider of claim 7, wherein the charging electrical conductor is connected to the
2 electronic feedback system, the charging electrical conductor applying the electrical charge
3 based upon a flying height of the slider.

1 9. The slider of claim 7, wherein the charging electrical conductor is connected to the
2 electronic feedback system, the charging electrical conductor applying the electrical charge
3 based upon a surrounding temperature of the slider.

1 10. The slider of claim 1, wherein the electrical charge ranges between 0.1 –5 volts.

1 11. A system, comprising:
2 a magnetic storage medium;
3 a suspension;
4 a slider coupled to the suspension;
5 a magnetic head coupled to the slider, the magnetic head having a first set of electrical
6 pads to read data from the magnetic storage medium and a second set of electrical pads to write
7 data to the magnetic storage medium;
8 a charging electrical pad coupled to the slider separate from the magnetic head; and
9 a charging electrical conductor coupled to the electrical pad to apply an electrical charge
10 to the slider.

- 1 12. The system of claim 11, wherein the charging electrical pad is coupled to a trailing edge
2 of the slider.
- 1 13. The system of claim 11, wherein the charging electrical pad is coupled to the slider
2 during a wafer fabrication process.
- 1 14. The system of claim 11, wherein the slider is electrically isolated from the suspension.
- 1 15. The system of claim 11, wherein the slider is coupled to the suspension using an adhesive
2 with a high electrical resistance.
- 1 16. The system of claim 11, wherein the slider is connected to an electronic feedback system,
2 the electronic feedback system to monitor an environmental condition of the slider.
- 1 17. The system of claim 16, wherein the charging electrical conductor is connected to the
2 electronic feedback system, the charging electrical conductor applying the electrical charge
3 based upon a flying height of the slider.
- 1 18. The system of claim 16, wherein the charging electrical conductor is connected to the
2 electronic feedback system, the charging electrical conductor applying the electrical charge
3 based upon a surrounding temperature of the slider.
- 1 19. The system of claim 11, wherein the electrical charge ranges between 0.1 –5 volts.

1 20. A method, comprising:
2 suspending a slider above a magnetic data storage medium, the slider coupled to a
3 charging electrical pad isolated electrically from a set of read electrical pads and a set of write
4 electrical pads on the slider;
5 applying an electrical voltage to the charging electrical pad to create an electrical charge
6 on the slider in relation to the magnetic data storage medium.

1 21. The method of claim 20, wherein the charging electrical pad is coupled to a trailing edge
2 of the slider.

1 22. The method of claim 20, wherein the charging electrical pad is coupled to the slider
2 during a wafer fabrication process.

1 23. The method of claim 20, wherein the slider is coupled to a suspension.

1 24. The method of claim 23, wherein the slider is electrically isolated from the suspension.

1 25. The method of claim 23, wherein the slider is coupled to the suspension using an
2 adhesive with a high electrical resistance.

1 26. The method of claim 20, further including monitoring environmental conditions of the
2 slider.

1 27. The method of claim 26, further including applying the electrical charge based upon a
2 flying height of the slider.

1 28. The method of claim 26, further including applying the electrical charge based upon a
2 surrounding temperature of the slider.

1 29. The method of claim 20, wherein the electrical charge ranges between 0.1 –5 volts.